

ABSTRACT OF THE DISCLOSURE

One or more semiconductor devices are packaged inside a stack-type semiconductor package. The stack-type semiconductor package has a printed circuit board having a circuit pattern. A 5 first semiconductor memory device (first device) is stacked on the PCB and is electrically connected to the PCB circuit pattern. A conductive frame has first terminals and second terminals, and the first terminals are electrically connected to the PCB circuit pattern. A second semiconductor memory device (second device) is 10 stacked on the conductive frame over the first device and is electrically connected to second terminals of the conductive frame. The second device is electrically connected to the PCB circuit pattern and the first device via the conductive frame. Each of the first device may be either a ball grid array type 15 stack package (BGA package) or a thin-small-outline-package-type package. The second device may be a BGA package.